

HUL7251

Hologram Unit

For optical information processing

Features

- Thin smaller package size achieved through micro-mirror integration
(3.3 × 6.8 × 4.3 mm)
- Fast response ($f_C = 35$ MHz)
- Focus error signal detection : SSD method
- Tracking error signal detection
: 3 beam method
- Low-power semiconductor laser included

Applications

- CD-ROM drives
(supports 20- to 24-time speed CD-ROM drives)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

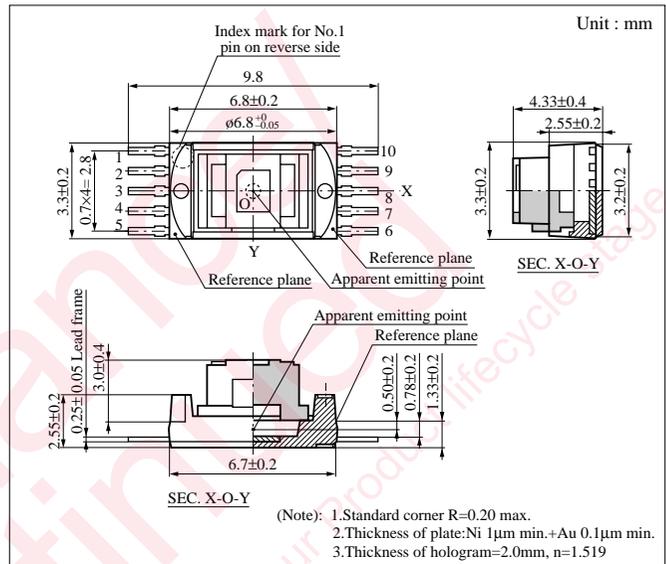
Parameter	Symbol	Rated	Unit
Laser beam output*1	P_O	0.3	mW
Reverse voltage	Laser	$V_{R(LD)}$	2 V
	Monitor	$V_{R(mon)}$	6 V
Supply voltage	V_R	6	V
Operating ambient temperature	T_{opr}	-10 to +60	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +85	$^\circ\text{C}$

*1 Light emitting output through objective lens

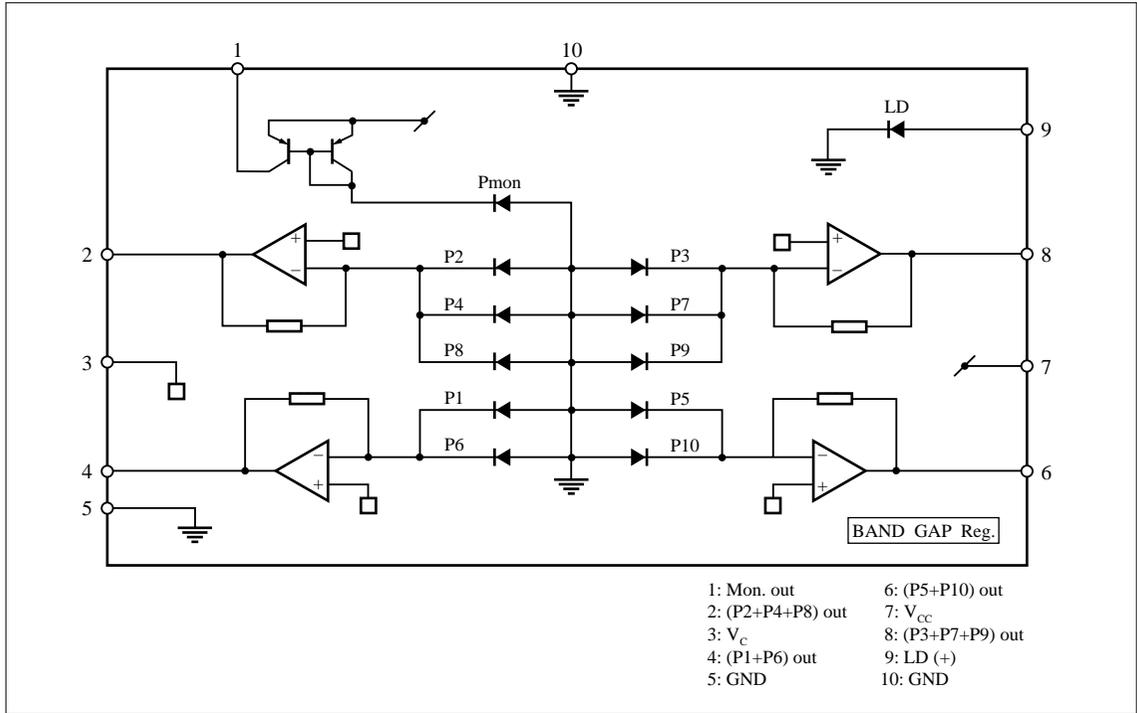
Electro-Optical Characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	min	typ	max	Unit
Laser beam output	P_O	CW		0.18	0.25	mW
Operating current	I_{OP}	CW $V_{RF} = 570\text{mV}$, $V_{CC} = 5\text{V}$	25	35	45	mA
Operating voltage	V_{OP}	CW $V_{RF} = 570\text{mV}$, $V_{CC} = 5\text{V}$		1.9	2.4	V
Oscillating wavelength	λ_L	CW $V_{RF} = 570\text{mV}$, $V_{CC} = 5\text{V}$	775	795	815	nm
Focus error signal amplitude	V_{FE}	CW $V_{RF} = 570\text{mV}$, $V_{CC} = 5\text{V}$	340	480	620	mV
Tracking error signal amplitude	V_{TE}	CW $V_{RF} = 570\text{mV}$, $V_{CC} = 5\text{V}$	150	300	450	mV
Focus error signal pull-in range	D_{FE}	CW $V_{RF} = 570\text{mV}$, $V_{CC} = 5\text{V}$	9	12	16	μm
Frequency characteristics (-3 dB)	f_C		30	35		MHz

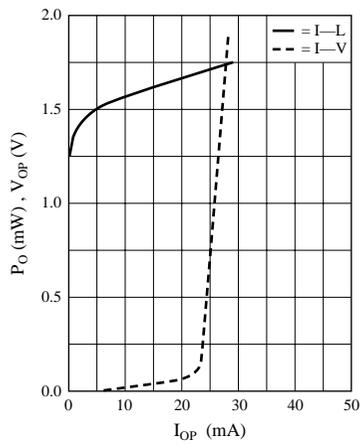
*1 Light emitting output through objective lens



■ Block Diagram of Circuit Functions



I—L, I—V



Caution for Safety

 **DANGER**

■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

■ Do not touch or look into the laser beam directly.

The laser beam may cause injury to the eye or skin, or loss of eyesight.

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